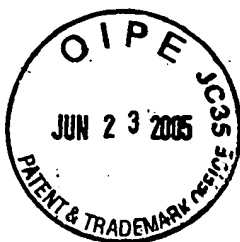


MEG-01-004



June 18, 2005

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Ave
Poughkeepsie, NY 12603

Subject: | Serial No. 09/837,007 04/18/01 |
| Mou-Shiung Lin |
"A STRUCTURE AND MANUFACTURING
METHOD OF A CHIP SCALE PACKAGE"
Grp. Art Unit: 2829 D. Zarneke

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated February 18, 2005,
please consider the following remarks regarding the above-
identified application for patent:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents, P.O.
Box 1450, Alexandria, VA 22313-1450, on JUNE 20, 2005.

Stephen B. Ackerman, Reg. No. 37,761

Signature [Signature]
Date 6/20/05

MEG-01-004

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 6 of this paper.